Hybrid 7p171 Traveler

June 30, 2000

1 Connectivity

Repairs on shorts:
Fixes for opens: BECLK, FECLK, Bus 7 Open on the hybrid. Fixed.

2 Chips

The following chips were assembled on this hybrid (in the order that the chips get read out):
Hybrid 7P171 has die: 240-020 233-054 233-056 233-057 233-062 233-063 233-064

3 Data Analysis Summary

The following summarizes the findings of the Burn-in data analysis program. The first chip in the readout name is numbered 0.

```
% Hybrid 7p171 classification info. Created 08:58:20 06/29/00

Hybrid 7p171 quality: fair
Chip classification: good good good fair good good good
Bad channels (chip-channel): 3-36
Bad cells: none
Random bad capacitors: none
Channels at pedestal needed for DCMS: 31.7 32.6 30.2 29.7 31.3 31.5 30.6
```

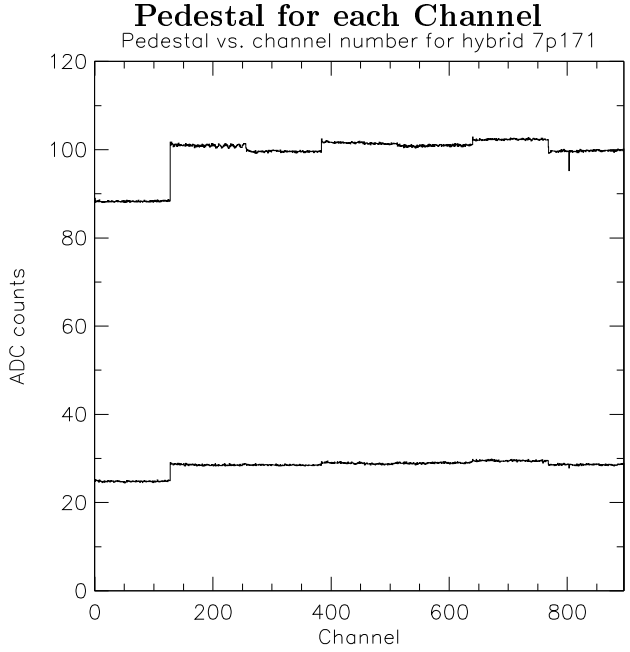
4 Comments

Encapsulated. FE DV finger gold bonds. HV tested. Chip 1 replaced.

5 Pedestal

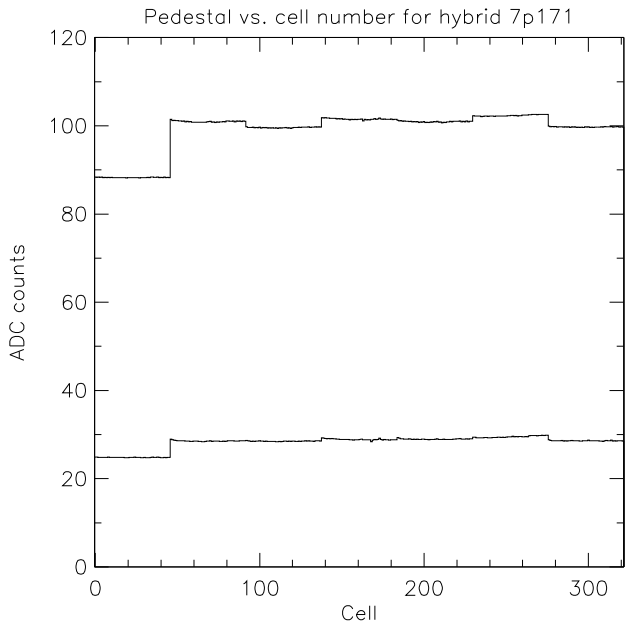
The following plot shows the pedestals vs. channel number with and without charge injection:

Pedestal for each Channel



The following plot shows the average pedestal vs. pipeline cell ID with and without charge injection. The x-axis is cell ID offset by 46 for each chip. Thus cell ID 5 for chip 1 is at x=5, chip 2 at x=51, chip 3 at x=97, etc.

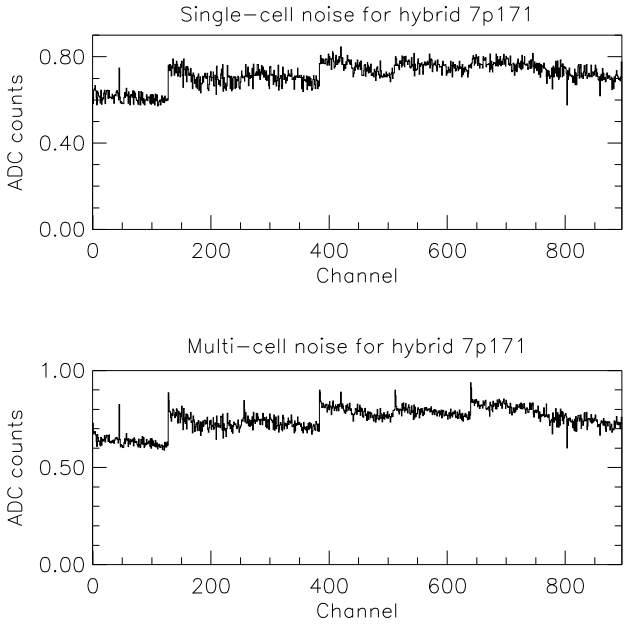
Pedestal vs. Pipeline Cell ID



6 Noise

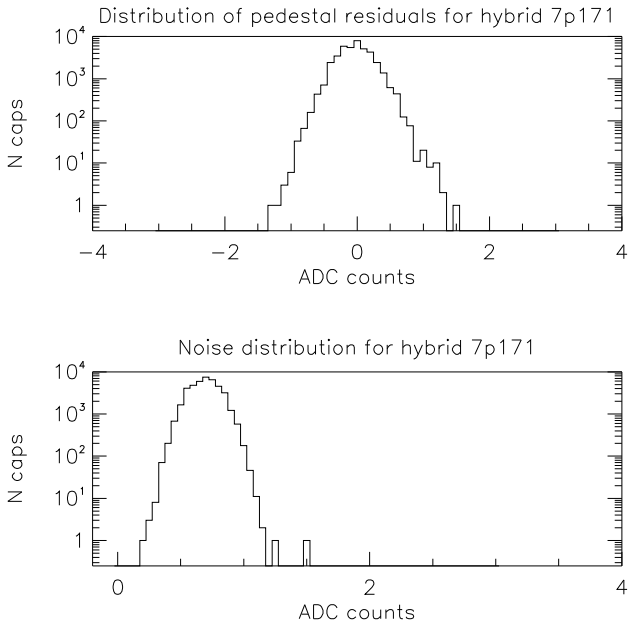
The following plots show the single-cell and multi-cell RMS noise:

RMS Noise

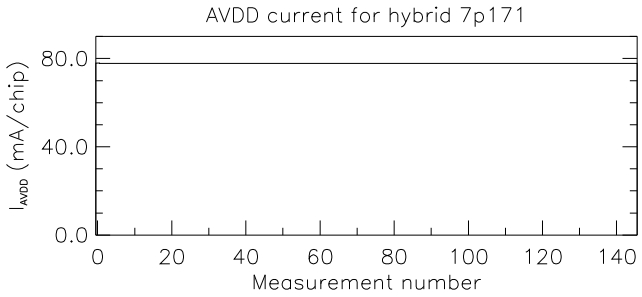
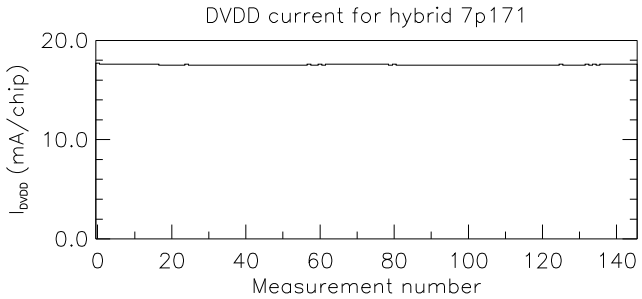


The following are histograms of the pedestal of each pipeline capacitor relative to the chip average (top); and the RMS noise of each capacitor (bottom):

Distribution of Pedestals and Noise



7 Currents

The following plots show the supply currents per chip as a function of measurment number. Currents are measured approximately every 10 minutes:

Supply Currents During Burn-in